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~~2. (Amended) A device according to claim 1, wherein the carrier element comprises a plastic material.~~

~~3. (Amended) A device according to claim 1, wherein the components of the electrical circuit arranged on the side of the electrically conductive structure facing the carrier element are at least partly embedded in the carrier element.~~

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~~9. (Amended) A device according to claim 1, wherein components of the electrical circuit are also arranged on a side of the electrically conductive structure remote from the carrier element, said components on the side of the electrically conductive structure remote from the carrier element being adhesively secured or soldered on said structure.~~

~~10. (Amended) A device according to claim 1, wherein the components of the electrical circuit arranged on the side of the electrically conductive structure facing the carrier element comprise active or passive components.~~

~~11. (Amended) A device according to claim 1, wherein the components of the electrical circuit arranged on the side of the electrically conductive structure facing the carrier element comprise one or more connecting devices for electrical connection of the arrangement to other components of the system containing the arrangement.~~

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~~13. (Amended) A device according to claim 1, wherein the components of the electrical circuit arranged on the side of the electrically conductive structure facing the carrier element are elements designed for surface mounting.~~

~~14. (Amended) A method for manufacture of a device having an electrical circuit carried by a carrier element and having an electrically conductive structure~~

provided on a surface of the carrier element as a component of the electrical circuit,
the method comprising the steps of:

- a) applying the electrically conductive structure to a side of a temporary substrate,
- b) mounting further components of the electrical circuit on the electrically conductive structure the further components being positioned on a side of the electrically conductive structure opposite from the temporary substrate,
- c) applying a composition forming the carrier element to the side of the temporary substrate, having the applied electrically conductive structure and
- d) removing the temporary substrate.

15. (Amended) A method according to claim 4, wherein applying the electrically conductive structure to the side of the temporary substrate comprises applying a single-layer or multi-layer thin-film structure to the temporary structure.

16. (Amended) A method according to claim 14, wherein applying the electrically conductive structure to the side of the temporary substrate comprises applying a single-layer or multi-layer thick-film structure to the temporary substrate.

17. (Amended) A method according to claim 14, wherein applying the electrically conductive structure to the side of the temporary substrate comprises applying one or more single-layer or multi-layer electrically conductive films to the temporary substrate.

18. (Amended) A method according to claim 14, wherein applying the electrically conductive structure to the side of the temporary substrate is effected such that the layer structure of the electrically conductive structure is opposite to the layer structure of the electrically conductive structure present in the finished arrangement on the carrier element.

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20. (Amended) A method according to claim 14, wherein applying the composition forming the carrier element is effected by casting or injection-moulding plastics material at least partly around the further components of the electrical circuit.

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22. (Amended) A method according to claim 14, wherein after removing the temporary substrate additional components of the electrical circuit are mounted on a side of the electrically conductive structure remote from the carrier element.

Please add the following new claims.

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23. (New) The device of Claim 9 wherein the components on the side of the electrically conductive structure remote from the carrier element are adhesively secured or soldered on the electrically conductive structure.

24. (New) The device of Claim 10 wherein the active or passive components comprise at least one semiconductor chip.

25. (New) The device of Claim 11 wherein the connecting devices comprise at least one electrical connector.

26. (New) The device of Claim 13 wherein the elements designed for surface mounting are soldered or adhesively secured to the side of the electrically conductive structure facing the carrier element.